

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4313190

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE BY SECURED PARTY (SEE DOCUMENT FOR DETAILS)
CONVEYING PARTY DATA	
Name	Execution Date
SILICON VALLEY BANK, AS COLLATERAL AGENT	01/14/2015
RECEIVING PARTY DATA	
Name:	AWBSCQEMGK, INC. (F/K/A ALTA DEVICES, INC.)
Street Address:	545 OAKMEAD PARKWAY
City:	SUNNYVALE
State/Country:	CALIFORNIA
Postal Code:	94085
PROPERTY NUMBERS Total: 6	
Property Type	Number
Patent Number:	9337014
Patent Number:	9356183
Patent Number:	9267205
Patent Number:	9136422
Patent Number:	9175393
Patent Number:	9114464
CORRESPONDENCE DATA	
Fax Number:	(202)857-6395
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2028576000
Email:	patentdocket@arentfox.com
Correspondent Name:	ARENT FOX LLP
Address Line 1:	1717 K STREET, NW
Address Line 4:	WASHINGTON DC, D.C. 20006-5344
ATTORNEY DOCKET NUMBER:	037620.00283
NAME OF SUBMITTER:	KINNON MCDONALD
SIGNATURE:	/KINNON MCDONALD/
DATE SIGNED:	03/10/2017
Total Attachments: 13	

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RELEASE OF SECURITY INTEREST

This RELEASE, dated as of January 14, 2015, is made by Awbscqemgk, Inc. (F/K/A ALTA DEVICES, INC.), a Delaware corporation ("Alta"), with reference to the patent security agreement executed by Alta in favor of SILICON VALLEY BANK, AS COLLATERAL AGENT, a national association ("SV Bank") (such agreement, as amended, restated, supplemented or otherwise modified from time to time, the "Patent Security Agreement"), which was recorded with the United States Patent and Trademark Office on:

1. April 10, 2013, at reel and frame number 30192/0391.

Capitalized terms not defined in this Release shall have the meanings set forth in the Patent Security Agreement.

Alta executes this Release pursuant to the Pay-Off Letter, dated July 7, 2014, among SV Bank, Gold Hill Capital 2008, LP ("Gold Hill", and together with SV Bank, the "Lenders") and Alta (a copy of which is attached as Exhibit A hereto) (the "Pay-Off Letter"), in which SV Bank, as agent for the Lenders, authorizes Alta, as Borrower, to file and record any "documents, releases or instruments necessary to release or terminate any lien with respect to Borrower's property or assets (including Borrower's intellectual property)".

For good and valuable consideration, receipt of which is hereby acknowledged, Alta hereby acknowledges and agrees that:

1. pursuant to the Pay-Off Letter, SV Bank previously released the security interest granted to SV Bank by Alta with respect to all Patents described in the Patent Security Agreement, including, but not limited to, the Patents listed on Exhibit B attached hereto (collectively, the "Alta Patents"); and

2. to the extent SV Bank shall have been deemed to have any right, title or interest in the Alta Patents, such right, title or interest was retransferred and reassigned to Alta by virtue of the Pay-Off Letter without representation or warranty of any kind whatsoever.

Alta hereby authorizes and requests that the Commissioner for Patents and Trademarks and any other governmental official record this Release. This Release shall be governed by the laws of the State of California.

IN WITNESS WHEREOF, the undersigned has caused this Release to be executed by its duly authorized officer as of the date first written above.

AWBSCQEMGK, INC. (F/K/A ALTA DEVICES, INC.)

By: _____

Name: John C. Barry
Title: CEO
Date: 1/14/2015

EXHIBIT A

Pay-Off Letter

[attached]



July 7, 2014

Alta Devices Incorporated
545 Oakmead Parkway
Sunnyvale, CA 94085

Re: Pay-Off Letter

We refer to the Loan and Security Agreement dated as of August 4, 2008 (as the same may from time to time have been amended, restated, or otherwise modified, the "Loan Agreement") by and among Gold Hill Capital 2008, LP ("GH Capital"), Silicon Valley Bank ("Bank") (GH Capital and Bank each individually, a "Lender" and collectively, the "Lenders"), Bank in its capacity as agent for the Lenders ("Agent"), and Alta Devices Inc. ("Borrower"). Capitalized terms used but not otherwise defined herein shall have the meanings given them in the Loan Agreement. The parties hereto hereby acknowledge that Gold Hill Venture Lending 03, LP is not a Lender under the Loan Agreement because all Growth Capital Advances have been paid in full and Gold Hill Venture Lending 03, LP only made Growth Capital Advances under the Loan Agreement.

Lenders acknowledge that Borrower is party to an Asset Purchase Agreement between Borrower and Hanergy Holding Group Company Limited ("Hanergy") dated November 27, 2013, as amended (the "APA").

Borrower has advised Lenders that it intends to repay, or cause to be repaid under the terms of the APA, all amounts due and owing under the Loan Agreement and has requested that Agent provide Borrower with appropriate pay-off amounts for the principal, interest, fees and other amounts owing by Borrower to Lenders under the Loan Documents (as defined below) (such amounts, collectively, the "Obligations"). The pay-off amounts as determined by Agent for Borrower as of July 7, 2014 (the "Computation Date") under the Loan Documents are as follows (collectively, together with any additional interest accruing after the Computation Date that must be repaid by Borrower, the "Pay-Off Amount"):

Principal	\$ 8,166,493.55
Interest	\$ 10,888.66
Restructure Fee	\$ 400,000.00
Final Payment	\$ 787,500.00
Statement Fee	\$ 15.00
Legal Fees	\$ 50,000.00
Total Amount Owning	\$ 9,414,897.21

From and after the Computation Date and until the Pay-Off Date (as defined below), interest shall continue to accrue on the unpaid principal amount at the rate set forth in the Loan Agreement. The per diem accrual of interest on the unpaid principal amount is \$1,814.78. Upon request of Borrower, Agent shall provide Borrower with a revised figure for the amount of interest to be paid as a part of the Pay-Off Amount. The foregoing accrued interest amount assumes no change in the operative interest rates after the date hereof. The foregoing principal balance assumes (1) no

force and effect, as if the payment or proceeds had never been received by such Lenders, and this letter shall in no way impair the claims of such Lender with respect to the revived Obligations.

On the Pay-Off Date, Agent (i) shall, and hereby authorizes Borrower or its designee to, file and record all UCC-3 Termination Statements to terminate all UCC Financing Statements in Lenders' favor with respect to Borrower and any of Borrower's property or assets and with respect to any third party and any of its property or assets that guaranteed the Obligations or provided collateral security therefore, and execute, deliver and acknowledge (and authorize Borrower or its designees to file and record) any other documents, releases or instruments necessary to release or terminate any lien with respect to Borrower's property or assets (including Borrower's intellectual property; (ii) shall (and authorizes Borrower or its designees to) deliver notices to terminate any deposit or securities account control agreements relating to any assets in which Borrower or any other party has pledged a security interest to Lenders to secure the obligations arising under the Loan Documents; and (iii) shall, return any pledged stock in Agent's possession (if any) to the pledgor. All such agreements, documents, and instruments that are requested by Borrower to be delivered or filed by Agent on or after the Pay-Off Date shall be prepared at no cost or expense to Agent; provided, that any costs or expenses incurred by Agent with respect to such items (including all reasonable attorneys' fees in excess of the "Legal Fees" portion of the Pay-Off Amount) shall be reimbursed promptly by Borrower on demand.

The Borrower hereby unconditionally releases, waives and forever discharges (i) any and all liabilities, obligations, duties, promises or indebtedness of any kind of the Agent and the Lenders to the Borrower, and (ii) all claims, suits, causes of action, of any kind whatsoever (if any), whether against the Agent, the Lenders or any of their directors, officers, employees or agents with respect to the obligations to be performed on or prior to the Payoff Date by the Agent or the Lenders under the Loan Documents, in either case (i) or (ii), on account of any condition, act, omission, event, contract, liability, obligation, indebtedness, claim, cause of action, defense, circumstance or matter of any kind whatsoever which existed, arose or occurred at any time prior to the Payoff Date or which arises as a result of the execution of (or the satisfaction of any condition precedent or subsequent to) this letter.

This letter may be executed in counterparts, each counterpart shall be deemed an original, but all which together shall constitute one instrument. Delivery of this letter by facsimile or electronic transmission shall have the same effect as delivery of a manually executed counterpart hereof.

This letter agreement shall be governed by the laws of the State of California and shall become effective only when signed by Lenders and accepted by Borrower by its due execution in the space provided below.

Very truly yours,

SILICON VALLEY BANK

By: _____
Name: _____
Title: _____

GOLD HILL CAPITAL 2008, LP

By: Timothy Waterson
Name: Tim Waterson
Title: Partner
Gold Hill Capital

Acknowledged by:

ALTA DEVICES, INC.

By: _____
Name: _____
Title: _____
Date: _____

SVB ACCOUNT OFFICER - RETURN EXECUTED PAY-OFF LETTER TO AMD COLLATERAL GROUP

FOR BANK USE ONLY

☐ AMD COLLATERAL - RECEIVED _____

This letter agreement shall be governed by the laws of the State of California and shall become effective only when signed by Lenders and accepted by Borrower by its due execution in the space provided below.

Very truly yours,

SILICON VALLEY BANK

By: _____
Name: _____
Title: _____

GOLD HILL CAPITAL 2008, LP

By: Timothy Waterson
Name: Tim Waterson
Title: Partner
Gold Hill Capital

Acknowledged by:

ALTA DEVICES, INC.

By: James C. Barry
Name: James C. Barry
Title: CFO
Date: _____

SVB ACCOUNT OFFICER – RETURN EXECUTED PAY-OFF LETTER TO AMD COLLATERAL GROUP

FOR BANK USE ONLY

☐ AMD COLLATERAL – RECEIVED _____

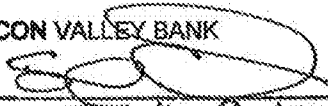
SVB Document - June 2008

PATENT
REEL: 041942 FRAME: 0294

This letter agreement shall be governed by the laws of the State of California and shall become effective only when signed by Lenders and accepted by Borrower by its due execution in the space provided below.

Very truly yours,

SILICON VALLEY BANK

By: 
Name: Sheila Colson
Title: Managing Director

GOLD HILL CAPITAL 2008, LP

By: _____
Name: _____
Title: _____

Acknowledged by:

ALTA DEVICES, INC.

By: _____
Name: _____
Title: _____
Date: _____

SVB ACCOUNT OFFICER -- RETURN EXECUTED PAY-OFF LETTER TO AMD COLLATERAL GROUP

FOR BANK USE ONLY

☐ AMD COLLATERAL -- RECEIVED _____

EXHIBIT B

United States Patents

Owner	Title	App. No.	App. Date	Patent No.	Issue Date
ALTA DEVICES, INC.	VAPOR DEPOSITION REACTOR SYSTEM	12725277	Mar 16, 2010		
ALTA DEVICES, INC.	METHOD FOR VAPOR DEPOSITION	12725296	Mar 16, 2010	8852696	Oct 7, 2014
ALTA DEVICES, INC.	WAFER CARRIER TRACK	12725308	Mar 16, 2010		
ALTA DEVICES, INC.	HEATING LAMP SYSTEM	12725314	Mar 16, 2010		
ALTA DEVICES, INC.	METHODS FOR HEATING WITH LAMPS	12725318	Mar 16, 2010	8859042	Oct 14, 2014
ALTA DEVICES, INC.	REACTOR LID ASSEMBLY FOR VAPOR DEPOSITION	12725332	Mar 16, 2010		
ALTA DEVICES, INC.	METHODS AND APPARATUS FOR A CHEMICAL VAPOR DEPOSITION REACTOR	13444645	Apr 11, 2012		
ALTA DEVICES, INC.	METHODS AND APPARATUS FOR A CHEMICAL VAPOR DEPOSITION REACTOR	12475131	May 29, 2009		
ALTA DEVICES, INC.	METHODS AND APPARATUS FOR A CHEMICAL VAPOR DEPOSITION REACTOR	12475169	May 29, 2009		
ALTA DEVICES, INC.	Concentric Showerhead For Vapor Deposition	12576797	Oct 9, 2009		
ALTA DEVICES, INC.	EPITAXIAL LIFT OFF STACK HAVING A NON-UNIFORM HANDLE AND METHODS THEREOF	13536043	Jun 28, 2012	8716107	May 6, 2014
ALTA DEVICES, INC.	EPITAXIAL LIFT OFF STACK HAVING A PRE-CURVED HANDLE AND METHODS THEREOF	12475406	May 29, 2009		
ALTA DEVICES, INC.	MESA ETCH METHOD AND COMPOSITION FOR EPITAXIAL LIFT OFF	12577645	Oct 12, 2009		
ALTA DEVICES, INC.	PHOTOVOLTAIC DEVICE	13772043	Feb 20, 2013		
ALTA DEVICES, INC.	PHOTOVOLTAIC DEVICE	12940861	Nov 5, 2010	8895845	Nov 25, 2014
ALTA DEVICES, INC.	PHOTOVOLTAIC DEVICE	12940876	Nov 5, 2010	8895846	Nov 25, 2014

INC.					
ALTA DEVICES, INC.	PHOTOVOLTAIC DEVICE	12605108	Oct 23, 2009		
ALTA DEVICES, INC.	THIN ABSORBER LAYER OF A PHOTOVOLTAIC DEVICE	12940918	Nov 5, 2010	8669467	Mar 11, 2014
ALTA DEVICES, INC.	PHOTOVOLTAIC DEVICE INCLUDING AN INTERMEDIATE LAYER	12940955	Nov 5, 2010	8912432	Dec 16, 2014
ALTA DEVICES, INC.	THIN ABSORBER LAYER OF A PHOTOVOLTAIC DEVICE	12605129	Oct 23, 2009	8674214	Mar 18, 2014
ALTA DEVICES, INC.	PHOTOVOLTAIC DEVICE WITH INCREASED LIGHT TRAPPING	12940966	Nov 5, 2010	8895847	8895847 Nov 25, 2014
ALTA DEVICES, INC.	PHOTOVOLTAIC DEVICE WITH INCREASED LIGHT TRAPPING	12605140	Oct 23, 2009	8686284	Apr 1, 2014
ALTA DEVICES, INC.	PHOTOVOLTAIC DEVICE WITH BACK SIDE CONTACTS	12605151	Oct 23, 2009		
ALTA DEVICES, INC.	INTEGRATION OF A PHOTOVOLTAIC DEVICE	12605163	Oct 23, 2009		
ALTA DEVICES, INC.	CHEMICAL VAPOR DEPOSITION REACTOR WITH ISOLATED SEQUENTIAL PROCESSING ZONES	13221780	Aug 30, 2011		
ALTA DEVICES, INC.	MULTIPLE STACK DEPOSITION FOR EPITAXIAL LIFT OFF	12632565	Dec 7, 2009		
ALTA DEVICES, INC.	VAPOR DEPOSITION REACTOR SYSTEM AND METHODS THEREOF	13257264	Dec 12, 2011		
ALTA DEVICES, INC.	WAFER CARRIER TRACK	13257269	Dec 12, 2011		
ALTA DEVICES, INC.	HEATING LAMP SYSTEM AND METHODS THEREOF	13257273	Nov 23, 2011		
ALTA DEVICES, INC.	SHOWERHEAD FOR VAPOR DEPOSITION	12725326	Mar 16, 2010		
ALTA DEVICES, INC.	REACTOR LID ASSEMBLY FOR VAPOR DEPOSITION	13257275	Nov 23, 2011		
ALTA DEVICES, INC.	TAPE-BASED EPITAXIAL LIFT OFF APPARATUSES AND METHODS	12640796	Dec 17, 2009		
ALTA DEVICES, INC.	TEXTURED METALLIC BACK REFLECTOR	12904047	Oct 13, 2010		
ALTA DEVICES,	REACTOR CLEAN	12913688	Oct 27, 2010		

INC.					
ALTA DEVICES, INC.	MIXED WIRING SCHEMES FOR SHADING ROBUSTNESS	12890368	Sep 24, 2010		
ALTA DEVICES, INC.	SUPPORT STRUCTURES FOR VARIOUS APPARATUSES INCLUDING OPTO-ELECTRICAL APPARATUSES	13012741	Jan 24, 2011		
ALTA DEVICES, INC.	HIGH GROWTH RATE DEPOSITION FOR GROUP III/V MATERIALS	12904090	Oct 13, 2010		
ALTA DEVICES, INC.	Epitaxial Lift Off Systems and Methods	13039307	Mar 2, 2011		
ALTA DEVICES, INC.	SUBSTRATE CLEAN SOLUTION FOR COPPER CONTAMINATION REMOVAL	13042379	Mar 7, 2011		
ALTA DEVICES, INC.	PHOTOVOLTAIC MODULE CONTAINING SHINGLED PHOTOVOLTAIC TILES AND FABRICATION PROCESSES THEREOF	13397487	Feb 15, 2012		
ALTA DEVICES, INC.	MOVABLE LINER ASSEMBLY FOR A DEPOSITION ZONE IN A CVD REACTOR	13222881	Aug 31, 2011		
ALTA DEVICES, INC.	THERMAL BRIDGE FOR CHEMICAL VAPOR DEPOSITION REACTORS	13222984	Aug 31, 2011		
ALTA DEVICES, INC.	METALLIC CONTACTS FOR PHOTOVOLTAIC DEVICES AND LOW TEMPERATURE FABRICATION PROCESSES THEREOF	12939050	Nov 3, 2010		
ALTA DEVICES, INC.	METHODS FOR FORMING OPTOELECTRONIC DEVICES INCLUDING HETEROJUNCTION	13451439	Apr 19, 2012		
ALTA DEVICES, INC.	OPTOELECTRONIC DEVICES INCLUDING HETEROJUNCTION AND INTERMEDIATE LAYER	13451455	Apr 19, 2012		
ALTA DEVICES, INC.	OFF-AXIS EPITAXIAL LIFT OFF PROCESS	13210138	Aug 15, 2011		
ALTA DEVICES, INC.	SELF-BYPASS DIODE FUNCTION FOR GALLIUM ARSENIDE PHOTOVOLTAIC DEVICES	13023733	Feb 9, 2011		
ALTA DEVICES, INC.	METAL CONTACT FORMATION AND WINDOW ETCH STOP FOR PHOTOVOLTAIC DEVICES	13023844	Feb 9, 2011		
ALTA DEVICES, INC.	SYSTEM AND METHOD FOR IMPROVED EPITAXIAL LIFT OFF	13078722	Apr 1, 2011	8657994	Feb 25, 2014
ALTA DEVICES, INC.	DEVICE AND METHOD FOR INDIVIDUAL FINGER ISOLATION IN AN OPTOELECTRONIC DEVICE	13222310	Aug 31, 2011	8846417	Sep 30, 2014

ALTA DEVICES, INC.	PHOTON RECYCLING IN AN OPTOELECTRONIC DEVICE	13223187	Aug 31, 2011		
ALTA DEVICES, INC.	CVD REACTOR WITH GAS FLOW VIRTUAL WALLS	13222840	Aug 31, 2011		
ALTA DEVICES, INC.	LASER CUTTING AND CHEMICAL EDGE CLEAN FOR THIN-FILM SOLAR CELLS	13223133	Aug 31, 2011	8728933	May 20, 2014
ALTA DEVICES, INC.	LASER CUTTING THROUGH TWO DISSIMILAR MATERIALS SEPARATED BY A METAL FOIL	13222686	Aug 31, 2011	8728849	May 20, 2014
ALTA DEVICES, INC.	METHOD AND APPARATUS FOR ASSEMBLING PHOTOVOLTAIC CELLS	13223242	Aug 31, 2011		
ALTA DEVICES, INC.	INDIVIDUAL FINGER ISOLATION THROUGH SPOT APPLICATION OF A DIELECTRIC IN AN OPTOELECTRONIC DEVICE	13222393	Aug 31, 2011		
ALTA DEVICES, INC.	OPTOELECTRONIC DEVICE WITH NON-CONTINUOUS BACK CONTACTS	13446876	Apr 13, 2012		
ALTA DEVICES, INC.	WHISPERING GALLERY SOLAR CELLS	13231111	Sep 13, 2011		
ALTA DEVICES, INC.	OPTOELECTRONIC DEVICES INCLUDING HETEROJUNCTION	12939077	Nov 3, 2010		
ALTA DEVICES, INC.	EPITAXIAL LIFT OFF STACK HAVING A UNIVERSALLY SHRUNK HANDLE AND METHODS THEREOF	12475411	May 29, 2009	8309432	Nov 13, 2012
ALTA DEVICES, INC.	EPITAXIAL LIFT OFF STACK HAVING A UNIDIRECTIONALLY SHRUNK HANDLE AND METHODS THEREOF	12475415	May 29, 2009	8003492	Aug 23, 2011
ALTA DEVICES, INC.	EPITAXIAL LIFT OFF STACK HAVING A NON-UNIFORM HANDLE AND METHODS THEREOF	12475418	May 29, 2009	8314011	Nov 20, 2012
ALTA DEVICES, INC.	EPITAXIAL LIFT OFF STACK HAVING A MULTI-LAYERED HANDLE AND METHODS THEREOF	12475420	May 29, 2009	12475420	Feb 5, 2013
ALTA DEVICES, INC.	CONTINUOUS FEED CHEMICAL VAPOR DEPOSITION	12577641	Oct 12, 2009	8008174	Aug 30, 2011
ALTA DEVICES, INC.	TILED SUBSTRATES FOR DEPOSITION AND EPITAXIAL LIFT OFF PROCESSES	12715243	Mar 1, 2010	8362592	Jan 29, 2013
ALTA DEVICES, INC.	FILM TRANSFER FRAME	13077353	Mar 31, 2011	8403315	Mar 26, 2013
ALTA DEVICES, INC.	TWO BEAM BACKSIDE LASER DICING OF SEMICONDUCTOR FILMS	13222617	Aug 31, 2011	8399281	Mar 19, 2013
ALTA	ALIGNED FRONTSIDE BACKSIDE	13222750	Aug 31,	8361828	Jan 29, 2013

DEVICES, INC.	LASER DICING OF SEMICONDUCTOR FILMS		2011		
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